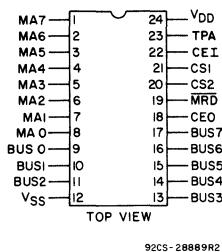


CDP1833, CDP1833C, CDP1833BC



CMOS 1024-Word x 8-Bit Static Read-Only Memory

Features:

- *CDP1833BC is compatible with the CDP1802BC 5 MHz microprocessor*
- *On-chip address latch*
- *Interfaces with CDP1800-series microprocessors without additional components*
- *Optional programmable location within 64K memory space*
- *Three-state outputs*

TERMINAL ASSIGNMENT

The RCA-CDP1833, CDP1833C, and CDP1833BC are static 8192-bit mask-programmable CMOS read-only memories organized as 1024-words x 8 bits and are completely static; no clocks are required. They will directly interface with the CDP1800-series microprocessors without additional components.

The CDP1833, CDP1833C, and CDP1833BC respond to a 16-bit address multiplexed on 8 address lines. Address latches are provided on-chip to store the 8 most significant bits of the 16-bit address. By mask option, this ROM can be programmed to operate in any 1024-word block within 64K memory space. The polarity of the high-address strobe (TPA), CEI, CS1, and CS2 are user mask-programmable.

The Chip-Enable output signal (CEO) is "high" when the device is selected. Terminals CEO and CEI can be

connected in a daisy chain to control selection of RAM memory in a microprocessor system without additional components.

The CDP1833C and CDP1833BC are functionally identical to the CDP1833. The CDP1833 has a recommended operating voltage range of 4 to 10.5 volts, and the CDP1833C and CDP1833BC have a recommended operating voltage range of 4 to 6.5 volts. The CDP1833BC is designed to interface with the CDP1802BC microprocessor.

The CDP1833, CDP1833C, and CDP1833BC are supplied in 24-lead hermetic dual-in-line side-brazed ceramic package (D suffix) and 24-lead dual-in-line plastic package (E suffix). The CDP1833C is also available in chip form (H suffix).

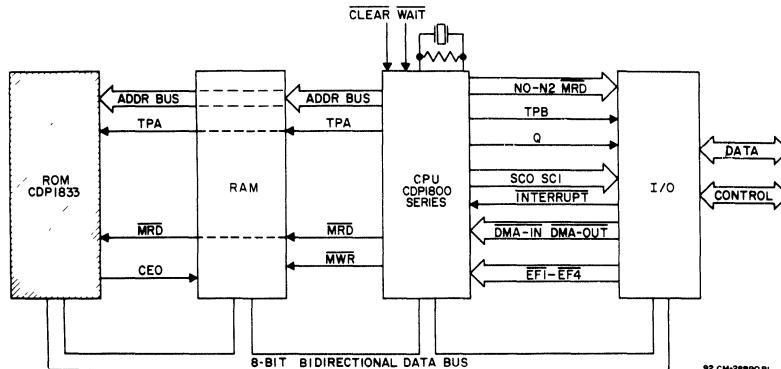


Fig. 1 - Typical CDP1800 Series microprocessor system.

CDP1833, CDP1833C, CDP1833BC**MAXIMUM RATINGS, Absolute-Maximum Values:**

DC SUPPLY-VOLTAGE RANGE, (V _{DD}) (Voltage referenced to V _{SS} terminal)	-0.5 to +11 V
CDP1833	-0.5 to +7 V
CDP1833C, CDP1833BC	-0.5 to V _{DD} +0.5 V
INPUT VOLTAGE RANGE, ALL INPUTS	-0.5 to V _{DD} +0.5 V
DC INPUT CURRENT, ANY ONE INPUT	±10 mA
POWER DISSIPATION PER PACKAGE (P _D)		
For TA = -40 to +60°C (PACKAGE TYPE E)	500 mW
For TA = +60 to +85°C (PACKAGE TYPE E)	Derate Linearly at 12 mW/°C to 200 mW
For TA = -55 to +100°C (PACKAGE TYPE D)	500 mW
For TA = +100 to 125°C (PACKAGE TYPE D)	Derate Linearly at 12 mW/°C to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR		
For TA = FULL PACKAGE-TEMPERATURE RANGE (All Packages)	100 mW
OPERATING-TEMPERATURE RANGE (TA):		
PACKAGE TYPE D	-55 to +125°C
PACKAGE TYPE E	-40 to +85°C
STORAGE TEMPERATURE RANGE (T _{STG})	-65 to +150°C
LEAD TEMPERATURE (DURING SOLDERING):		
At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s max	+265°C

OPERATING CONDITIONS at TA = -40° to +85°C

For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS				UNITS	
	CDP1833		CDP1833C, CDP1833BC			
	Min.	Max.	Min.	Max.		
DC Operating Voltage Range	4	10.5	4	6.5	V	
Input Voltage Range	V _{SS}	V _{DD}	V _{SS}	V _{DD}		

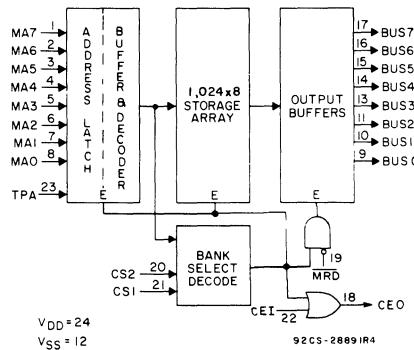


Fig. 2 – Functional diagram.

CDP1833, CDP1833C, CDP1833BCSTATIC ELECTRICAL CHARACTERISTICS at $T_A = -40$ to $+85^\circ C$, $V_{DD} \pm 5\%$, Except as noted

CHARACTERISTIC	CONDITIONS			LIMITS						UNITS	
	V_O (V)	V_{IN} (V)	V_{DD} (V)	CDP1833			CDP1833C, CDP1833BC				
				Min.	Typ.*	Max.	Min.	Typ.*	Max.		
Quiescent Device Current I_{DD}	—	5	5	—	0.01	50	—	0.02	200	μA	
	—	10	10	—	1	200	—	—	—		
Output Low Drive (Sink) Current I_{OL}	0.4	0, 5	5	0.8	—	—	0.8	—	—	mA	
	0.5	0, 10	10	1.8	—	—	—	—	—		
Output High Drive (Source) Current I_{OH}	4.6	0, 5	5	-0.8	—	—	-0.8	—	—	mA	
	9.5	0, 10	10	-1.8	—	—	—	—	—		
Output Voltage Low-Level V_{OL}	—	0, 5	5	—	0	0.1	—	0	0.1	V	
	—	0, 10	10	—	0	0.1	—	—	—		
Output Voltage High Level V_{OH}	—	0, 5	5	4.9	5	—	4.9	5	—	V	
	—	0, 10	10	9.9	10	—	—	—	—		
Input Low Voltage V_{IL}	0.5, 4.5	—	5	—	—	1.5	—	—	1.5	V	
	1, 9	—	10	—	—	3	—	—	—		
Input High Voltage V_{IH}	0.5, 4.5	—	5	3.5	—	—	3.5	—	—	V	
	1, 9	—	10	7	—	—	—	—	—		
Input Leakage Current I_{IN}	Any	0, 5	5	—	$\pm 10^{-4}$	± 1	—	$\pm 10^{-4}$	± 1	μA	
	Input	0, 10	10	—	$\pm 10^{-4}$	± 2	—	—	—		
3-State Output Current I_{OUT}	0, 5	0, 5	5	—	$\pm 10^{-4}$	± 1	—	$\pm 10^{-4}$	± 1	μA	
	0, 10	0, 10	10	—	$\pm 10^{-4}$	± 2	—	—	—		
Operating Device Current I_{DD1+}	—	0, 5	5	—	7	10	—	7	10	mA	
	—	0, 10	10	—	14	20	—	—	—		
Input Capacitance C_{IN}	—	—	—	—	5	7.5	—	5	7.5	pF	
Output Capacitance C_{OUT}	—	—	—	—	10	15	—	10	15		

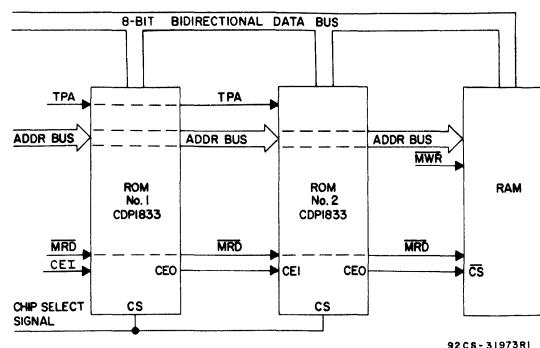
* Typical values are for $T_A = 25^\circ C$ and nominal V_{DD} .† Outputs open-circuit; cycle time = $2.5 \mu s$ 

Fig. 3 – Daisy chaining CDP1833's.

"Daisy Chaining" with CEI inputs and CEO outputs is used to avoid memory conflicts between ROM and RAM in a user system. In the above configuration, if ROM #1 was masked-programmed for memory locations 0000-03FF₁₆ and ROM

#2 masked-programmed for memory locations 0400₁₆-07FF₁₆, for address from 0000-07FF₁₆ the RAM would be disabled and the ROM enabled. For locations above 07FF₁₆ the ROM's would be disabled and the RAM enabled.

CDP1833, CDP1833C, CDP1833BC

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = -40$ to $=85^\circ\text{C}$, $V_{DD} \pm 5\%$,
Input $t_r, t_f = 10$ ns, $C_L = 50$ pF, $R_L = 200$ k Ω

CHARACTERISTIC	TEST CONDITIONS	V _{DD} (V)	LIMITS									UNITS	
			CDP1833			CDP1833C			CDP1833BC				
			Min.#	Typ.#	Max.	Min.#	Typ.#	Max.	Min.#	Typ.#	Max.		
Access Time From Address Change	t _{AA}	5	—	650	775	—	650	775	—	575	700	ns	
		10	—	350	425	—	—	—	—	—	—		
Access Time From Chip Select	t _{ACS}	5	—	500	625	—	500	625	—	475	600	ns	
		10	—	275	310	—	—	—	—	—	—		
Chip Select Delay	t _{CS}	5	—	250	320	—	250	320	—	250	320	ns	
		10	—	125	180	—	—	—	—	—	—		
Address Setup Time	t _{AS}	5	75	50	—	75	50	—	75	50	—	ns	
		10	40	25	—	—	—	—	—	—	—		
Address Hold Time	t _{AH}	5	100	75	—	100	75	—	75	50	—	ns	
		10	50	30	—	—	—	—	—	—	—		
Read Delay	t _{MRD}	5	—	400	500	—	400	500	—	400	500	ns	
		10	—	200	275	—	—	—	—	—	—		
Chip Enable Output Delay from Address	t _{CA}	5	—	120	170	—	120	170	—	120	170	ns	
		10	—	70	100	—	—	—	—	—	—		
Bus Contention Delay	t _{PAW}	5	—	220	270	—	220	270	—	220	270	ns	
		10	—	130	150	—	—	—	—	—	—		
TPA Pulse Width	t _{CEIO}	5	200	—	—	200	—	—	175	—	—	ns	
		10	70	—	—	—	—	—	—	—	—		
Chip Enable In to Chip Enable Out Delay	t _{CEIO}	5	—	200	250	—	200	250	—	200	250	ns	
		10	—	100	150	—	—	—	—	—	—		

Time required by a limit device to allow for the indicated function.

- Time required by a typical device to allow for the indicated function. Typical values are for $T_A = 25^\circ\text{C}$ and nominal voltages

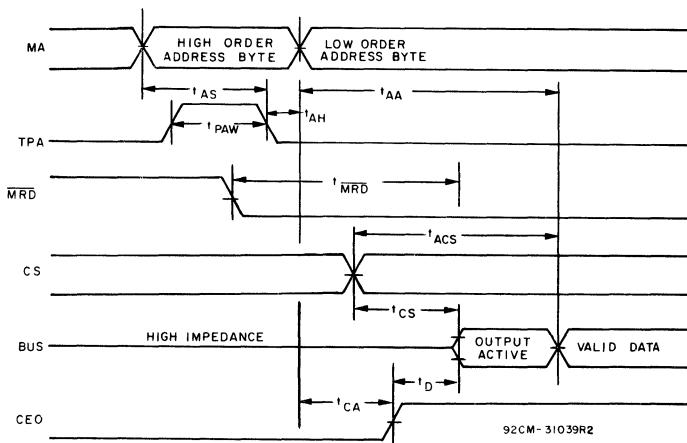


Fig. 4 - Timing waveforms.

CDP1833, CDP1833C, CDP1833BC

Note:

The dynamic characteristics and timing diagrams indicate maximum performance capability of the CDP1833. When used directly with a CDP1800-series microprocessor, timing will be determined by the clock frequency and internal delays of the microprocessor.

The following general timing relationships will hold when the CDP1833 is used with a CDP1800-series microprocessor.

$$t_{AH} = 0.5 \text{ } t_c$$
$$t_{PAW} = 1 \text{ } t_c$$

MRD occurs one clock period (t_c) earlier than the address bits MA0-MA7.

$$\text{where } t_c = \frac{1}{\text{CPU clock frequency}}$$